

UNIXX D20(30)

SEMI-AUTOMATIC DEVELOPING SYSTEMS

BENEFITS

- ÷ Semi-automated system with manual loading and unloading
- ÷ For Si-, Glas-, Ceramic wafer and compound material
- ÷ Substrates sizes up to Ø300mm or up to 230 x 230 mm
- ÷ Electronic media arm up to 6 media lines
- ÷ Different types of nozzles
- ÷ Automatic or fix splash ring
- ÷ Standard or customized chucks
- ÷ User-friendly operation and multi-user interfaces
- ÷ Designed for R&D and small-scale production



UNIXX D20 (200mm)
Advanced developing system

UNIXX D30 (300mm)
Standard developing system

ADVANCED DEVELOPER UP TO 300 MM (12 INCH)

SEMI-AUTOMATIC DEVELOPING,
CLEANING AND DRYING SYSTEM.



Bench mounted module
UNIXX DB20



PROPERTIES

Advanced developer module with movable splash ring provide high quality processing applications with manual load-/unload of single substrates.

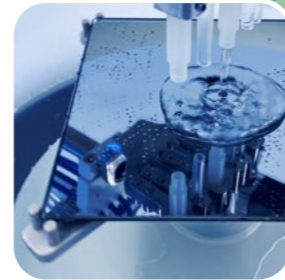
Benefits with splash-ring lift:

- ÷ Advanced developing, cleaning and drying processing
- ÷ For small pieces
- ÷ Round wafers up to Ø200 (Ø300) mm
- ÷ Square substrates up to 150x150 (230x230) mm
- ÷ Automatic splash-ring lift
- ÷ Vacuum- or low-contact centrifugal force chucks with BSR through the middle
- ÷ High quality such as the module for our fully automatic system

Properties for all developer types:

- ÷ Manual load-/unloading
- ÷ Chucks for round wafer square substrate or small piece
- ÷ For Si-, Glas-, Ceramic substrates
- ÷ 1x Dispense arm for max. 6 media lines
- ÷ Different types of nozzles
- ÷ Media supply by pressure canister or pump system
- ÷ Spin Motor with wobble effect
- ÷ Process bowls for different media drain separations (1, 2 or 3-way separations)
- ÷ Start-stop buttons on the device or via the control unit
- ÷ Emergency stop button at systems front
- ÷ Software provides user-friendly operation and multi-user interfaces
- ÷ System design available as a bench mounted module or stand-alone systems.

Optional; external media supply cabinet with 10 or 20 ltr. canister.



**PROVIDES
HIGH
QUALITY**

UNIXX D20/30 (ADVANCED)

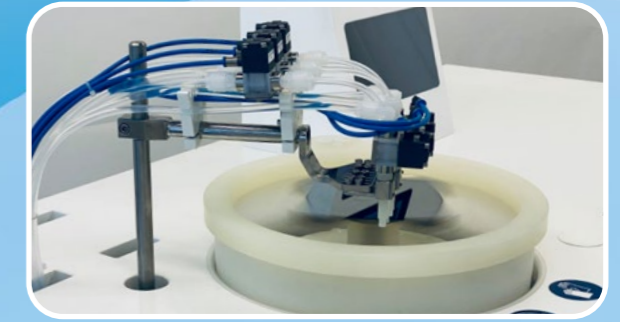
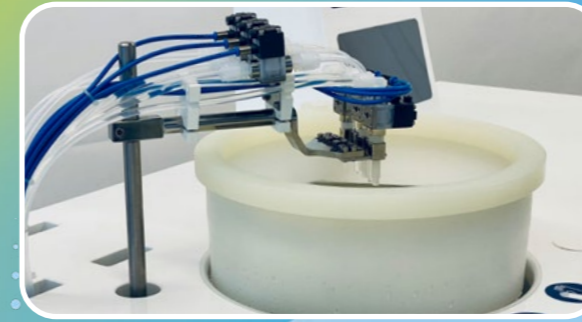
SEMI-AUTOMATIC DEVELOPER

The UNIXX DB20 semi-automatic developer processing module provides high quality such as the module for our fully automatic system.

UNIXX DB20/30 supports round wafers up to 300 mm (Ø12 inch) or square substrates 230 x 230 mm (9 x 9 inch).

It's designed for developing, cleaning & drying processes with multi puddle-, spray- and megasonic & atomizing nozzles. In combination with the temperature-controlled option for heated media lines and a low contact chuck, provide this module the best developing processing.

The processing area is easy to clean and it's resistant to all kind of used developer chemical.



WITH AUTOMATIC SPLASH-RING LIFT

HIGH QUALITY SUCH AS THE MODULE FOR OUR FULLY AUTOMATIC SYSTEM

SPIN MOTOR WITH WOBBLE EFFECT DEVELOPER

TECHNICAL DATA (UNIXX D20/30) ADVANCED

GENERAL

Substrate size:	up to Ø200 mm (Ø8 inch) or 150x150 mm (6x6 inch) up to Ø300 mm (Ø12 inch) or 230x230 mm (9x9 inch)
Motor spin speed:	max. 10.000 rpm*, programmable in 1 rpm steps
Motor acceleration:	max. 40.000 rpm/sec*, in 1 rpm/sec steps
Step time:	1 up to 999.9 sec, in 0.1 sec steps
System frame:	made of powder-coated stainless steel, 4 adjustable feet and transport wheels
System housing:	made of powder-coated stainless steel
Process bowl:	made of PP natural

**depending on chuck design, substrate weight and load*

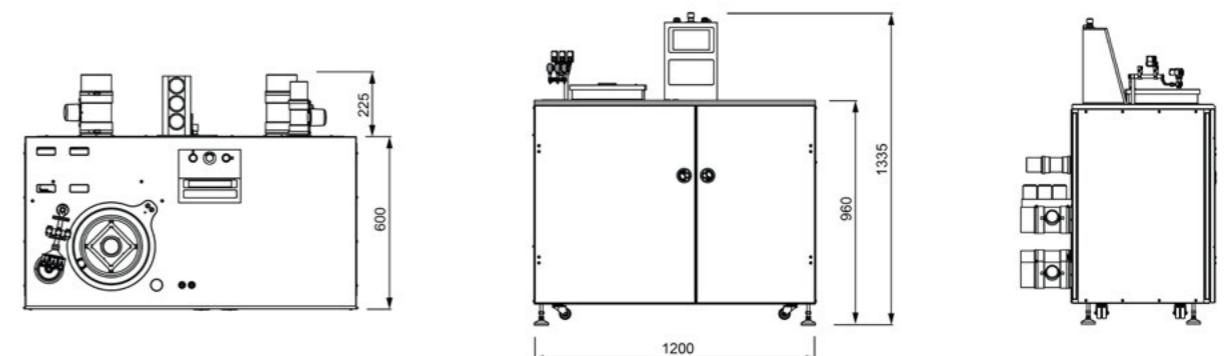
REQUIREMENTS

Power:	400(208) VAC / 3Phase / N / PE / 50(60) Hz
Vacuum:	-0.8 bar, tube OD Ø8mm
CDA:	8 bar, tube OD Ø10 mm
Nitrogen:	4.5 bar, tube OD Ø10 mm
DI-Water:	2-3 bar, OD Ø16.7 mm (3/8")
Exhaust process:	1x OD Ø110 mm, 50 - 120m ³ /h*
Exhaust cabinet:	2x OD Ø110 mm, 50 - 180m ³ /h*
Drain:	to waste canister with high level sensor or to the facility drain*

**chemical and process related*

DIMENSIONS (WXDXH) approx.

Double base frame: 1200 x 600/825 x 960/1.335 mm (47.3 x 23.6/32.5 x 38/52.6 inch)



STANDARD DEVELOPER UP TO 300 MM (12 INCH)

SEMI-AUTOMATIC DEVELOPING,
CLEANING AND DRYING SYSTEM.



Bench mounted module
UNIXX DB30

PROPERTIES

Standard developer module is designed to provide users in science, and research with a productive, safe and clean system.

Benefits with standard splash-ring:

- ÷ Standard developing, cleaning and drying processing
- ÷ For small pieces
- ÷ Round wafers up to Ø200 (Ø300) mm
- ÷ Square substrates up to 150x150 (230x230) mm
- ÷ Three-piece process bowl or as one-way bowl
- ÷ Fixed height of the splash-ring
- ÷ Vacuum- or low-contact chucks with BSR nozzle in the bowl
- ÷ Transparent plastic lid with safety interrupt sensor
- ÷ Lower investment costs

Properties for all developer types:

- ÷ Manual load-/unloading
- ÷ Chucks for round wafer square substrate or small piece
- ÷ For Si-, Glas-, Ceramic substrates
- ÷ 1x Dispense arm for max. 6 media lines
- ÷ Different types of nozzles
- ÷ Media supply by pressure canister or pump system
- ÷ Spin Motor with wobble effect
- ÷ Process bowls for different media drain separations (1, 2 or 3-way separations)
- ÷ Start-stop buttons on the device or via the control unit
- ÷ Emergency stop button at systems front
- ÷ Software provides user-friendly operation and multi-user interfaces
- ÷ System design available as a bench mounted module or stand-alone systems.

Optional; external media supply cabinet with 10 or 20 ltr. canister.



CHUCKS FOR LOW CONTACT WITH ONLY 3-4 CONTACT POINTS AT THE EDGE AND 100% BSR

PRODUCTIVE, SAFE AND CLEAN SYSTEM

PROGRAMMABLE MEDIA ARM

TECHNICAL DATA (UNIXX D20/30) STANDARD

GENERAL

Substrate size:	up to Ø200 mm (Ø8 inch) or 150x150 mm (6x6 inch) up to Ø300 mm (Ø12 inch) or 230x230 mm (9x9 inch)
Motor spin speed:	max. 10.000 rpm*, programmable in 1 rpm steps
Motor acceleration:	max. 40.000 rpm/sec*, in 1 rpm/sec steps
Step time:	1 up to 999.9 sec, in 0.1 sec steps
System frame:	made of powder-coated stainless steel, 4 adjustable feet and transport wheels
System housing:	made of powder-coated stainless steel
Process bowl:	made of PP natural
Process cover:	transparent plastic lid

*depending on chuck design, substrate weight and load

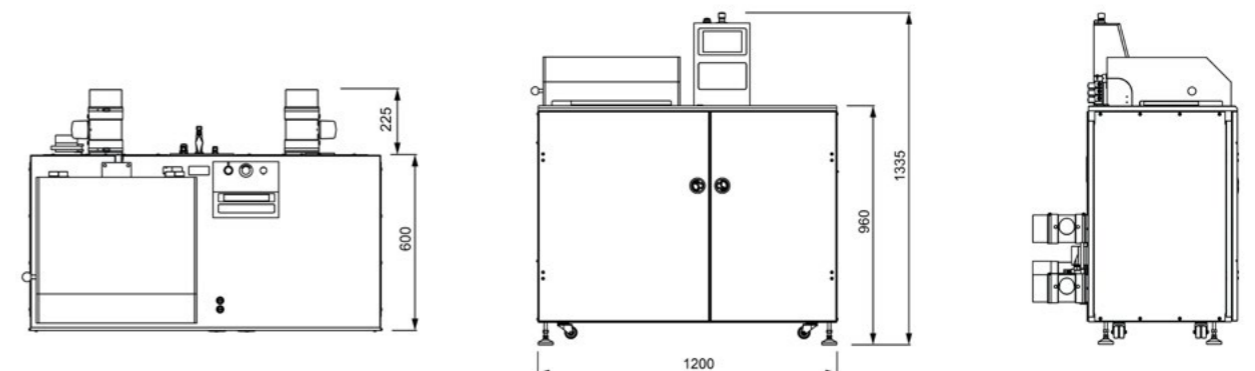
REQUIREMENTS

Power:	400(208) VAC / 3 Phase / N / PE / 50(60) Hz
Vacuum:	-0.8 bar, tube OD Ø8mm
CDA:	8 bar, tube OD Ø10 mm
Nitrogen:	4.5 bar, tube OD Ø10 mm
DI-Water:	2-3 bar, OD Ø16.7 mm (3/8")
Exhaust process:	1x OD Ø110 mm, 50 - 120m ³ /h*
Exhaust cabinet:	2x OD Ø110 mm, 50 - 180m ³ /h*
Drain:	to waste canister with high level sensor or to the facility drain*

*chemical and process related

DIMENSIONS (WXDXH) approx.

Double base frame: 1200 x 600/825 x 960/1.335 mm (47.3 x 23.6/32.5 x 38/52.6 inch)



**PRODUCTIVE
SAFE & CLEAN
SYSTEM**

UNIXX DB20/30 (STANDARD)

SEMI-AUTOMATIC DEVELOPER

The UNIXX DB20/30 developer modules are designed for developing, cleaning & drying processes with puddle-, spray- and megasonic & atomizing nozzles.

UNIXX DB20/30 supports round wafers up to 300 mm or square substrates 230 x 230 mm. A media arm equipped with up to 6 puddle nozzles or with various spray nozzles offers excellent development processing. The device has an easy-to-operate user interface with all needed functions such as recipe programming, service communications, and user administration.

All necessary media supplies such as CDA, N₂, Vacuum and DI-water can be connected via quick plug-in connections and controlled by software.



CONTROL UNIT (uiS)

UNIXX-Software (uiS) Osiris user interface

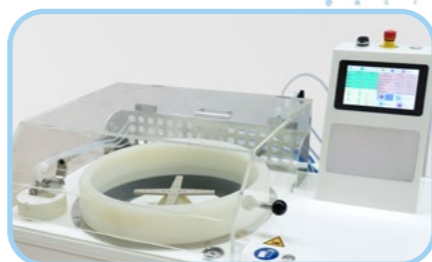
- ÷ 7"(10") color touch screen as user terminal
- ÷ Language: German, English, French or Spanish
- ÷ Recipe editor to write, manage and system configure.
- ÷ Recipe storage function on flash drive or memory stick.
- ÷ Library function for recipes, flows, log file (e.g. error tracking history)
- ÷ User management with password-protected service access.
- ÷ Update & backup function via USB or intranet connection



ELECTRICAL MEDIA ARM

- ÷ Dispense arm for max. 6 media lines/nozzles
- ÷ Motorized dispense arm (servomotor controlled)
- ÷ Movement speed programmable
- ÷ Target position programmable in 0.1 mm steps
- ÷ Filter system for solvent
- ÷ Drip pan (classic, comfort or deluxe design)

Optional: Temperature controlled dispense line

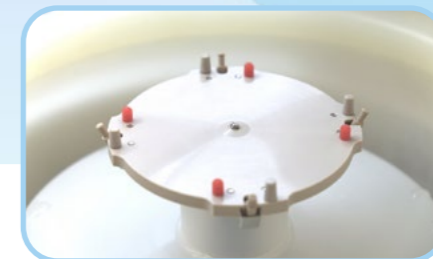
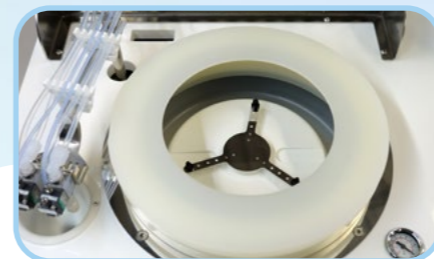


NOZZLE TYPES

- ÷ Puddle- (5-hole) nozzle
- ÷ Spray nozzle
- ÷ Megasonic nozzle
- ÷ Atomizing nozzle
- ÷ Nitrogen (N2) blow

- ÷ BSR (back side rinse) nozzle*
Two possible configurations:
» Manually adjustable nozzle in the bowl
» Static nozzle through the motor shaft

*depending on the chuck design



CHUCK DESIGNS

- ÷ with low contact points at the edge
- ÷ with Bernoulli effect to protect the backside
- ÷ with vacuum contact

OPTIONS

1. Customized chuck & inlay design
2. Integrated PR dispensing pumps (diaphragm or vacuum)
3. Temperature controlled dispense line
4. Media- and waste tanks
5. External media cabinets
6. Automatic programmable bowl wash function
7. Bowl for drain separations (1, 2 or 3-ways)



DESIGN VARIATIONS

System types available for up to 200mm or up to 300mm.

DEVELOPER - STANDARD & ADVANCED -

Bench mounted module

UNIXX DB20/DB30 Standard

Dimensions (WxDxH) approx.

650 x 650 x 600/1.000 mm (25.6 x 25.6 x 23.6/39.4 inch)



Single base frame - stand-alone system

UNIXX DA20/DA30 Standard

Dimensions (WxDxH) approx.

650 x 650/875 x 960/1.130 mm
(25.6 x 25.6/34.5 x 37.8/44.5 inch)

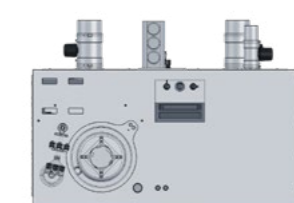


Double base frame - stand-alone system

UNIXX D20/D30 Advanced

Dimensions (WxDxH) approx.

1200 x 600/825 x 960/1.335 mm
(47.3 x 23.6/32.5 x 38/52.6 inch)





LOCATIONS

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